

SSCTXXX11D3

Low-Capacitance Bidirectional Micro Packaged TVS Diodes for ESD Protection

Description

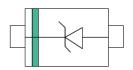
The SSCTXXX11D3 is designed with AF Punch-Through process TVS technology to protect voltage sensitive components from ESD. Excellent clamping capability,low leakage,and fast response time provide best in class protection on designs that are exposed to ESD.Because of its small size,it is suited for use in cellular phones,MP3 players,digital cameras and many other portable applications where board space comes at a premium. Also because of its low capacitance,it is suited for use in high frequency designs such as USB 2.0 high speed,VGA,DVI,SDI and other high speed line applications.

It has been specifically designed to protect sensitive components which are connected to data and transmission lines from overvoltage caused by ESD(electrostatic discharge), and EFT(electrical fast transients).

Feature

- ♦ Peak Power Dissipation-150 W(8 x 20 us Waveform)
- ♦ Stand-off Voltage: 5.0 V
- ♦ Replacement for MLV(0603)
- ♦ Protects I/O Port
- ♦ Meets MSL 1 Requirements
- ♦ ROHS compliant
- ♦ Solid-state Punch-Through TVS Process technology
- ♦ AF technology

PIN configuration



Applications

- ♦ High Speed Line:USB1.0/2.0,VGA,DVI,SDI,
- ♦ Serial and Parallel Ports
- ♦ Notebooks, Desktops, Servers
- ♦ Projection TV
- ♦ Cellular handsets and accessories
- ♦ Portable instrumentation
- ♦ Peripherals

Machanical data

- ♦ Lead finish:100% matte Sn(Tin)
- ♦ Mounting position:Any
- ♦ Qualified max reflow temperature:260°C
- ♦ Device meets MSL 1 requirements
- ♦ Pure tin plating:7~17 um
- ♦ Pin flatness:≤3mil

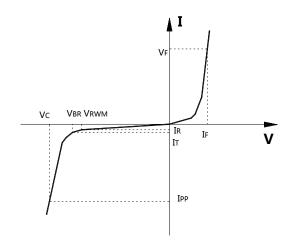
• Protection solution to meet

- \Rightarrow IEC61000-4-2(ESD) \pm 25kV(air), \pm 30kV(contact)
- ♦ IEC61000-4-4(EFT)40A(5/50ns)



• Electronic Parameter

Symbol	Parameter
V _{RWM}	Working Peak Reverse Voltage
V _{PT}	Punch-Through Voltage@ I _{PT}
V _{SB}	Snap-Back Voltage@ I _{SB}
V _C	Clamping Voltage @ IPP
I_{T}	Test Current
Irm	Leakage current at VRWM
Ірр	Peak pulse current
Co	Off-state Capacitance
C_{J}	Junction Capacitance



• Absolute maximum rating@TA=25°C

Symbol	Parameter	Value	Units
P_{PPP}	Peak Pulse Power(tp=8/20μs waveform)	150	Watts
	ESD Rating per IEC61000-4-2: Contact	25	1237
	Air	30	KV
TL	Lead Soldering Temperature	260(10 sec.)	$^{\circ}$
Тл	Operating Temperature Range	-55~150	$^{\circ}$
Tstg	Storage Temperature Range	-55~150	$^{\circ}$
TL	Lead Solder Temperature-Maximum(10 Second	260 ℃	
	Duration)		C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

Electrical Characteristics@TA=25°C

Device	*7	\mathbf{V}_{1}	BR	I _R @50 mA	\mathbf{v}_{c}	Capacitance
	$V_{ m RWM}$	(Vo	olts)	(uA)	@1 A	@V _R =2 V,1 MHz(pF)
	(V)	Тур	Max	Тур	(V)	Тур
SSCT5V011D3	5.0	6		1	9.8	40
SSCT12V11D3	12	13.3		1	18	75
SSCT24V11D3	24	27		2	40	80

Junction capacitance is measured in VR=0V,F=1MHz

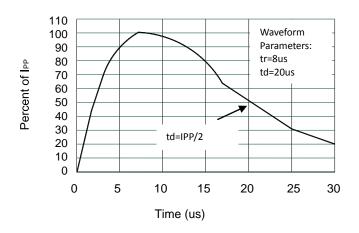
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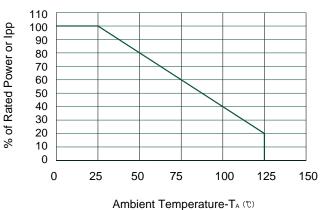
^{*}Other voltages may be available upon request.

^{1.} Non-repetitive current pulse, per Figure 1.



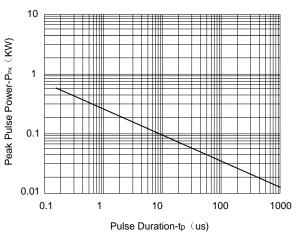
• Typical Performance Characteristics



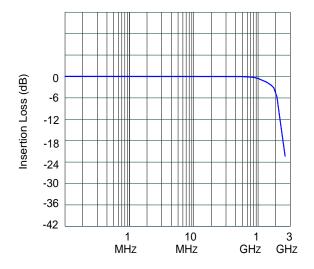


Pulse Waveform

Power Derating Curve





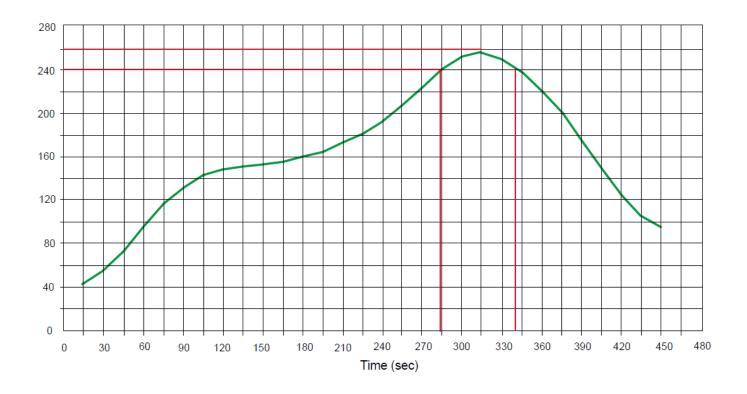


Non-Repetitive Peak Pulse Power vs. Pulse Time



• Solder Reflow Recommendation

Peak Temp=257°C,Ramp Rate=0.802deg.°C/sec





• Package Information

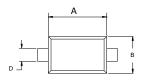
Ordering Information

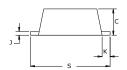
Device	Package	Qty per Reel	Reel Size
SSCT5V011D3	SOD-523	3000	7 Inch
SSCT12V11D3	SOD-523	3000	7 Inch
SSCT24V11D3	SOD-523	3000	7 Inch

Mechanical Data

Case:SOD-523

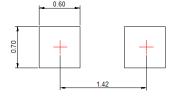
Case Material: Molded Plastic. UL Flammability





DIM	Millimeters		
	Min	Max	
Α	1.10	1.30	
В	0.75	0.85	
С	0.51	0.70	
D	0.25	0.35	
J	0.08	0.15	
К	0.15	0.25	
s	1.50	1.70	

Recommended Pad outline





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